

# SOT401-1

plastic low profile quad flat package; 32 leads; body 5 x 5 x 1.4 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	LQFP32
<b>Package type industry code</b>	LQFP32
<b>Package style descriptive code</b>	LQFP (low profile quad flat package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	136E01
<b>JEDEC package outline code</b>	MS-026
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	20-2-2003

Table 1. Package summary

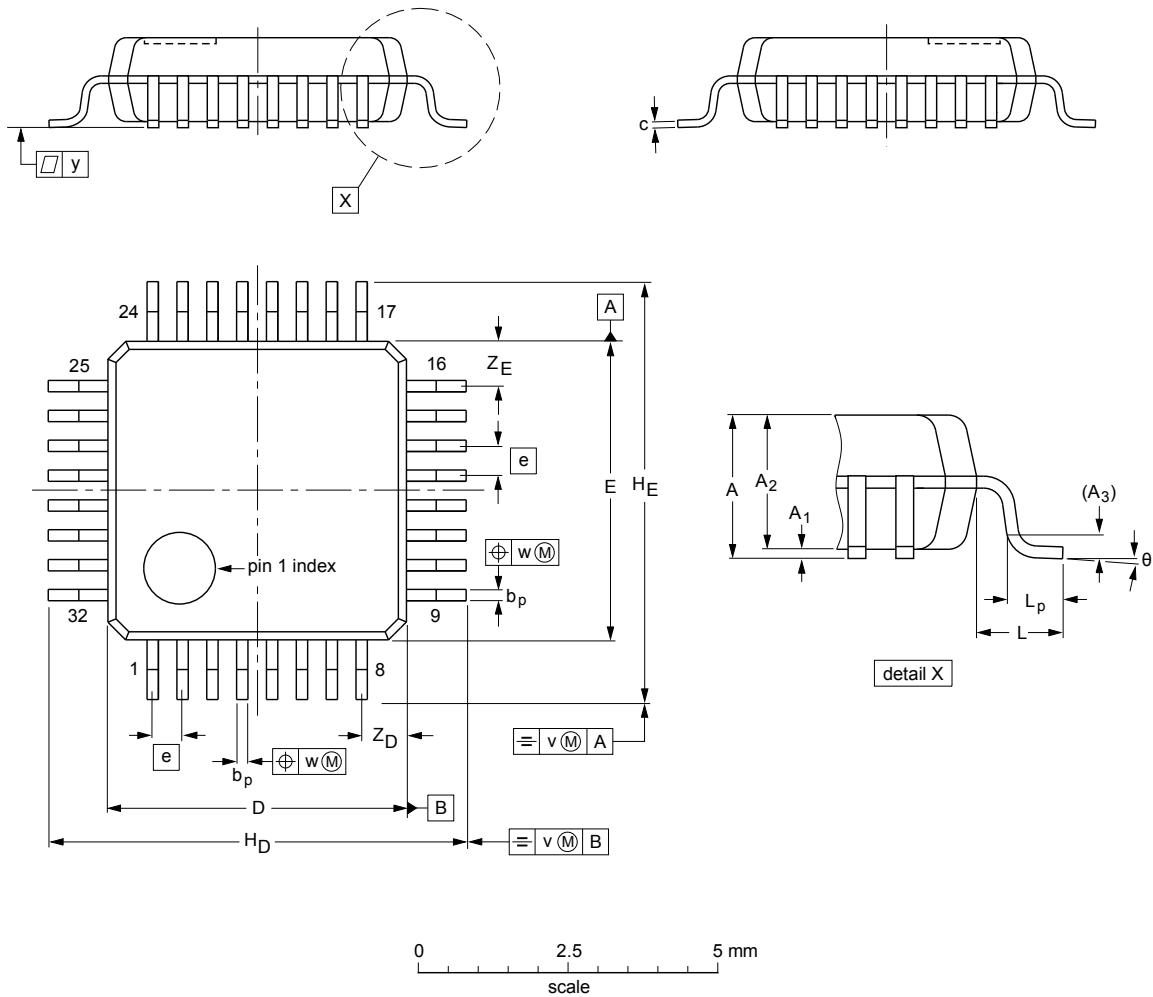
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.9	-	5	5.1	mm
E	package width	4.9	-	5	5.1	mm
A	seated height	[tbd]	-	1.6	1.6	mm
A <sub>2</sub>	package height	1.3	-	1.4	1.5	mm
n <sub>2</sub>	actual quantity of termination	-	-	32	-	



2. Package outline

LQFP32: plastic low profile quad flat package; 32 leads; body 5 x 5 x 1.4 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>D</sub>	H <sub>E</sub>	L	L <sub>p</sub>	v	w	y	Z <sub>D</sub> <sup>(1)</sup>	Z <sub>E</sub> <sup>(1)</sup>	θ
mm	1.6	0.15 0.05	1.5 1.3	0.25	0.27 0.17	0.18 0.12	5.1 4.9	5.1 4.9	0.5	7.15 6.85	7.15 6.85	1	0.75 0.45	0.2	0.12	0.1	0.95 0.55	0.95 0.55	7° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT401-1	136E01	MS-026				00-01-19 03-02-20

Fig. 1. Package outline LQFP32 (SOT401-1)

### 3. Soldering

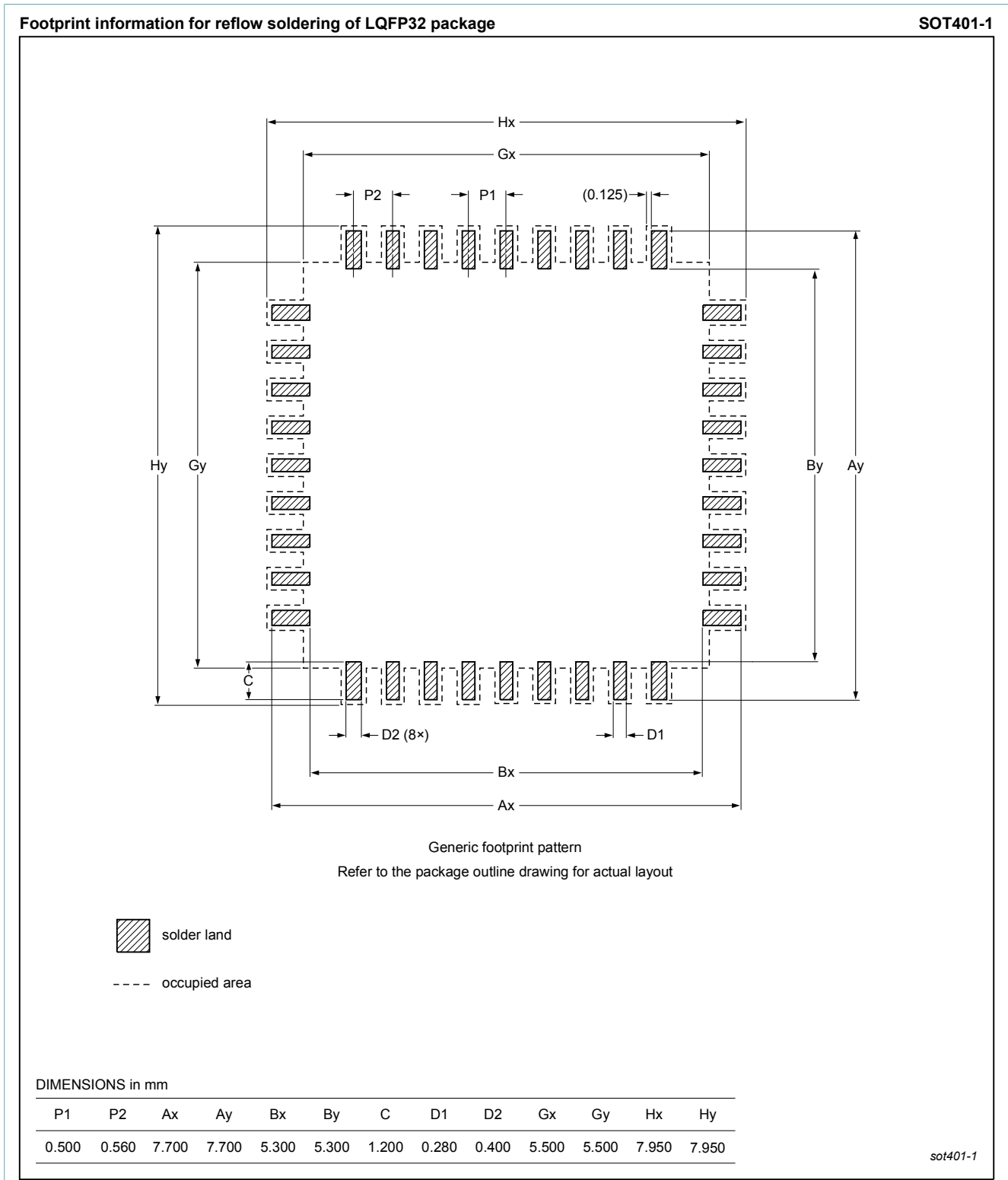


Fig. 2. Reflow soldering footprint for LQFP32 (SOT401-1)

## 4. Legal information

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Date of release: 8 February 2016

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